

ICDIS 2026

第三届集成电路设计与集成系统国际研讨会

3rd International Symposium on Integrated Circuit
Design and Integrated Systems

会议日程

Conference Program

中国呼和浩特（线上） | Hohhot, China (Online)

2026 年 8 月 3 日 | August 3, 2026

大会简介

第三届集成电路设计与集成系统国际研讨会

3rd International Symposium on Integrated Circuit Design and Integrated Systems

第三届集成电路设计与集成系统国际会议 (ICDIS 2026) 将于 2026 年 8 月 3 日在中国呼和浩特线上举办。本次会议旨在为从事集成电路、半导体、光电集成、电子硬件领域研究的专家、学者搭建国际化学术交流平台，届时将汇聚全球各地高校教授、科研人员、企业工程师，共同分享前沿研究成果，探讨行业技术难点、产业发展痛点与创新解决方案。

我们热忱邀请海内外科研工作者参会，交流集成电路全产业链最新技术成果、行业发展趋势与工程实践方案，互通研究思路，为跨学科、跨国界科研合作挖掘新思路、汲取创新灵感。

Introduction

第三届集成电路设计与集成系统国际研讨会

3rd International Symposium on Integrated Circuit Design and Integrated Systems

The 3rd International Symposium on Integrated Circuit Design and Integrated Systems (ICDIS 2026) will be held online in Hohhot, China on August 3, 2026. This conference aims to build an international academic exchange platform for experts and scholars engaged in integrated circuits, semiconductors, optoelectronic integration, electronic hardware and related research fields. It will gather university professors, researchers and enterprise engineers from all over the world to share cutting-edge research achievements, and discuss technical bottlenecks, industrial pain points and innovative solutions in the industry.

We sincerely invite researchers at home and abroad to attend the conference to exchange the latest technological achievements, industrial development trends and engineering practical solutions across the entire integrated circuit industrial chain, exchange research ideas, explore new perspectives and draw innovative inspirations for interdisciplinary and transnational research cooperation.

组织单位

第三届集成电路设计与集成系统国际研讨会

3rd International Symposium on Integrated Circuit Design and Integrated Systems

支持单位

三亚纵横能源研究院

巴西坎皮纳斯大学

大会主席

Mário F. S. Ferreira, 葡萄牙阿威罗大学

Esteban Tlelo-Cuautle, 墨西哥国立天体物理学、光学和电子学研究所

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Kamran Dawood, Astor Enerji, Turkey

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Luigi Fortuna, University of Catania, Italy

Mehdi Gheisari, Mehdi Gheisari Islamic Azad University, Iran

Mihaela Popescu, University of Craiova, Romania

Mohamad Sawan, Westlake University, China

Mohan Lal Kolhe, University of Agder, Norway

Muhammad Junaid, China University of Mining and Technology, China

Mukul Kumar, National Taiwan University, Taiwan

Paras Pandey, Amazon Web Services Fintech, USA

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Sourabh Jhavar, Apptad, USA

Taha Elwi, Al-Mammon University College, Iraq

Tee Hui Teo, Singapore University of Technology and Design, Singapore

Yoshiaki Daimon Hagiwara, Sojo University, Japan

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Taha Elwi, Al-Mammon University College, Iraq

Tee Hui Teo, Singapore University of Technology and Design, Singapore

Yoshiaki Daimon Hagiwara, Sojo University, Japan

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日期 / Date: 2026 年 08 月 03 日 (周一) | August 3, 2026 (Monday)

时区 / Time zone: UTC+8:00, 北京时间 | UTC+8:00, Beijing Time

腾讯会议室入会链接: <https://meeting.tencent.com/dm/nV9xZSt9RaJF>

VooV Meeting Link: <https://voovmeeting.com/dm/nV9xZSt9RaJF>

腾讯会议室入会 ID / VooV Meeting ID: 411-321-352

Time / 时间	Program / 日程
14:00-14:10	Opening Ceremony / 开幕式
14:10-14:40	Keynote Speech 1 / 主讲报告 1: Assoc. Prof. Muhammad Junaid China University of Mining and Technology, China / 中国矿业大学副教授
14:40-15:10	Keynote Speech 2 / 主讲报告 2: Prof. Anton Dianov Wenzhou University, China / 温州大学教授
15:10-15:40	Keynote Speech 3/ 主讲报告 3: Prof. Yoshiaki Daimon Hagiwara Sojo University, Japan / 日本崇城大学教授
15:40-16:10	Keynote Speech 4 / 主讲报告 4: Dr. Tee Hui Teo Singapore University of Technology and Design, Singapore / 新加坡科技设计大学高级讲师

16:10-16:40	Keynote Speech 5 / 主讲报告 5: Prof. Luigi Fortuna University of Catania, Italy / 意大利卡塔尼亚大学教授
16:40-18:00	Oral Presentation / 口头汇报